

Title (en)

Chip to board bus connection.

Title (de)

Verbindung zwischen einem Chip und einer Schaltungsplatte.

Title (fr)

Connexion entre une puce et un panneau de circuit.

Publication

EP 0188726 A2 19860730 (EN)

Application

EP 85115702 A 19851210

Priority

US 69124885 A 19850114

Abstract (en)

A configuration is disclosed for attaching leads (15) from several chips (1a-1d) to bus (5a) lines (9a-9m) on a printed circuit board (6). The bus (5a) includes pads (13), each directed toward one of pads (3) on the chip to be connected by arched wires (15). Lines (9a-91) connect to each end of the board pads (13) and extend generally parallel to the chips (1a-1d) past the sections containing the pads (3). Lines (9a-91) are displaced alternately toward and away from the chips (1a-1d) at sections containing pads (13) directed toward the chips (1a-1d) or having a part (17) taking a corresponding direction. The pads (13) alternate on opposite sides of each chip (1) to minimize the length of the leads (15) and to allow a central chip pad (3V) for carrying operating voltage (or ground) to connect to the outermost line (9m). This reduces the board space used for a bus (5a) and minimized the length of wires (15) connecting chips (1a-1d) to a bus (5a).

IPC 1-7

H01L 23/48; H01L 23/52

IPC 8 full level

H01L 21/60 (2006.01)

CPC (source: EP US)

H01L 24/49 (2013.01 - EP US); **H01L 24/85** (2013.01 - EP US); **H01L 24/48** (2013.01 - EP US); **H01L 2224/05554** (2013.01 - EP US); **H01L 2224/48227** (2013.01 - EP US); **H01L 2224/48247** (2013.01 - EP US); **H01L 2224/49171** (2013.01 - EP US); **H01L 2224/85** (2013.01 - EP US); **H01L 2924/00014** (2013.01 - EP US); **H01L 2924/01013** (2013.01 - EP US); **H01L 2924/01019** (2013.01 - EP US); **H01L 2924/01057** (2013.01 - EP US); **H01L 2924/14** (2013.01 - EP US); **H01L 2924/3025** (2013.01 - EP US)

Designated contracting state (EPC)

DE FR GB IT

DOCDB simple family (publication)

US 4580193 A 19860401; CA 1224277 A 19870714; DE 3585440 D1 19920402; EP 0188726 A2 19860730; EP 0188726 A3 19870513; EP 0188726 B1 19920226; JP H0237094 B2 19900822; JP S6156440 A 19860322

DOCDB simple family (application)

US 69124885 A 19850114; CA 497771 A 19851216; DE 3585440 T 19851210; EP 85115702 A 19851210; JP 17957685 A 19850816